



Model 835 Semiautomatic Pick and Place System

Manual X-Y precision slide table with 18" x 9" of travel, micro-adjustable table travel limits, large working surface in both X & Y directions with standardized mounting holes for various production tools. Single tool bonding arm with drop down control knob for tool rotation.



Specifications:

- +/- 25 micron placement accuracy
- 4" Vacuum stage standard
- Consistent bond load
- Throughput: Up to 400 Placements/hr

Options:

- Microscope
- Crosshair System
- Four 2" x 2" waffle pack stage
- Die Ejector Stage
- Dual Position Head for Epoxy Dispense

Dimensions:

- Weight: 85 lbs
- Power: 120 VAC or 220VAC
- Vacuum: 20 in/Hg

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